

[54] HEAT RELEASING PLATE FOR MOUNTING SEMICONDUCTOR COMPONENTS

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[**] Term: 14 Years

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[58] Field of Search D13/23; 165/80 R, 80 A, 165/80 B, 80 D; 357/81; 174/16 HS

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[57] CLAIM

The ornamental design for heat releasing plate for mounting semiconductor components, as shown and described.

DESCRIPTION

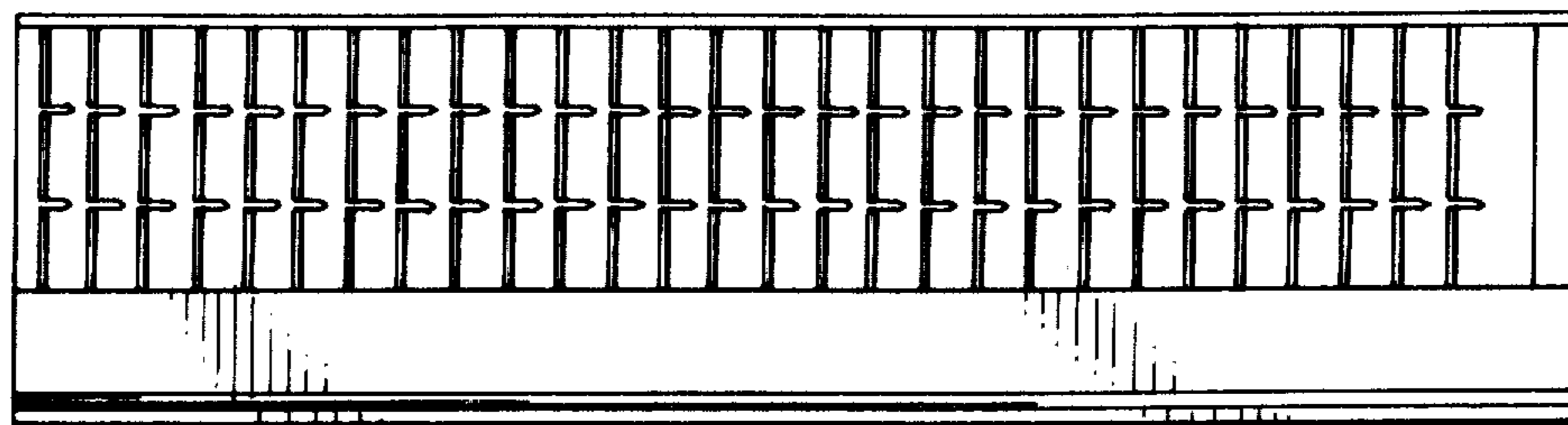
FIG. 1 is a front view of the heat releasing plate for mounting semi-conductor components showing the new design;

FIG. 2 is a plan view thereof;

FIG. 3 is a bottom view thereof;

FIG. 4 is a right side view thereof; and

FIG. 5 is a sectional view taken on line 5—5 of FIG. 2.



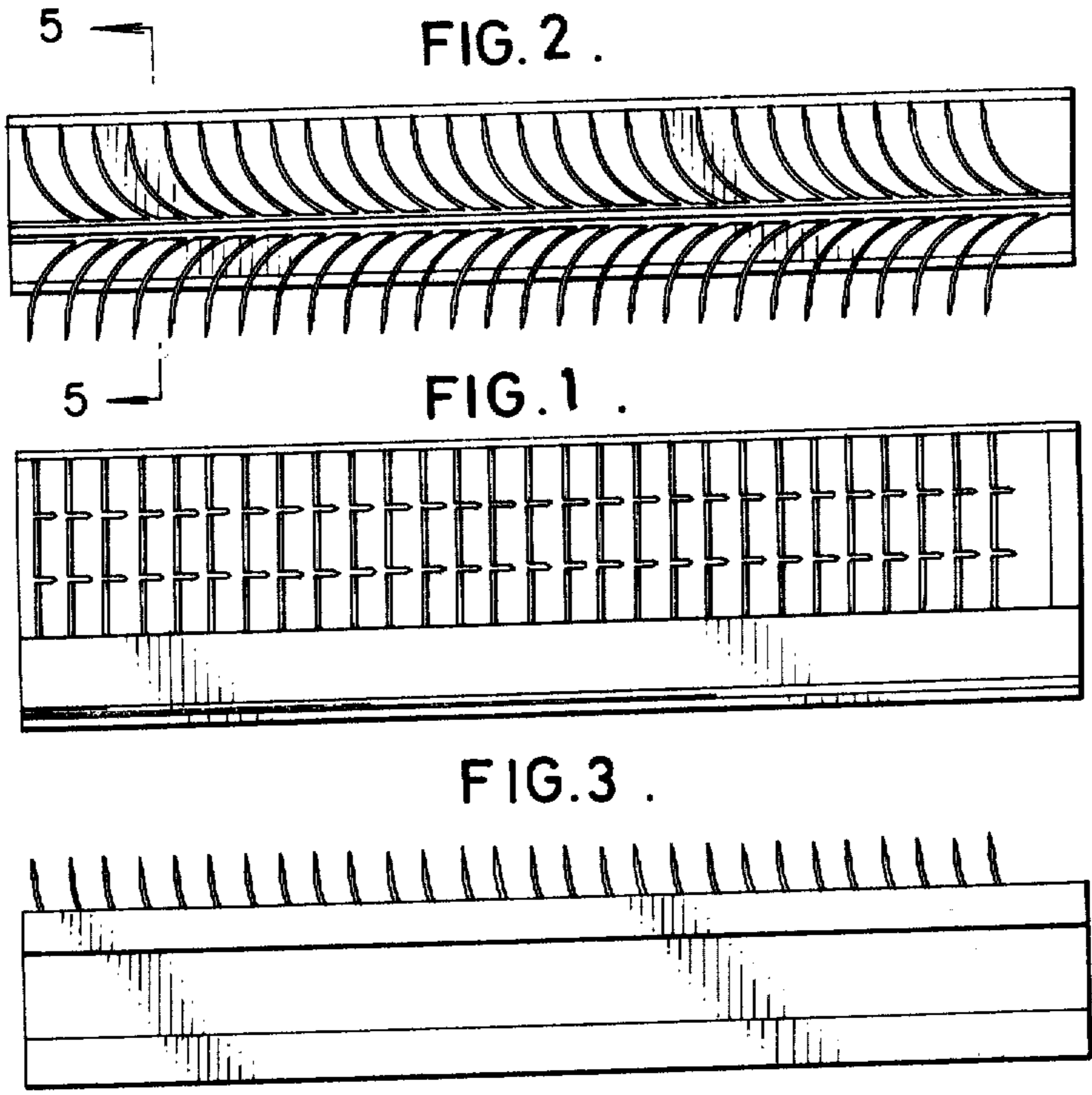


FIG. 4 .

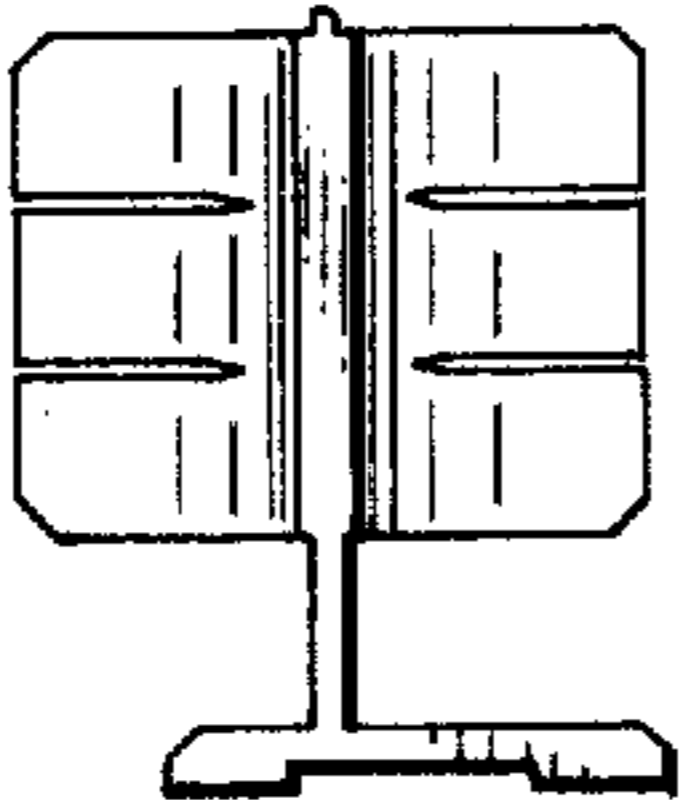


FIG. 5 .

